PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	ADG/22/13479
1.3 Title of PCN	SPC582BxxE1, SPC584BxxE1, SPC58xCxxE1, SPC584BxxE3, SPC58xCxxE3 (FC60,FC70,FC80): Activation of KESM as Additional Final Test and Burn-In Plant
1.4 Product Category	see list
1.5 Issue date	2022-06-20

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Luca RODESCHINI
2.1.2 Marketing Manager	Matteo MOIOLI
2.1.3 Quality Manager	Alberto MERVIC

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Testing (SOP 2617)	Subcontractor KESM – Malaysia (Receiving Plant)

4. Description of change

	Old	**New**
4.1 Description	ST Kirkop - Malta	ST Kirkop - Malta and Sub. KESM - Malaysia
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Capacity increase
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes

7. Timing / schedule

7.1 Date of qualification results	2022-09-15
7.2 Intended start of delivery	2022-09-30
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	**Issue Date**	

9. Attachments (additional documentations)

13479 Public product.pdf
13479 Details.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SPC582B50E1AD00X	
	SPC582B50E1CG00X	
	SPC582B60E1CD00X	
	SPC582B60E1MH00Y	
	SPC584B70E1NHC0X	
	SPC584B70E3EHC0X	

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PRODUCT/PROCESS CHANGE NOTIFICATION

TITLE	**SPC582BxxE1, SPC584BxxE1, SPC58xCxxE1, SPC584BxxE3, SPC58xCxxE3 (FC60,FC70,FC80): Activation of KESM as Additional Final Test and Burn-In Plant**
IMPACTED PRODUCTS	TQFP64 10x10x1.0 ExPad package: ✚ FC60 – Chorus 1M – assembled in Muar ✚ FC70 – Chorus 2M – assembled in Muar ✚ FC80 – Cut2.0 – Chorus 4M – assembled in Muar TQFP100 14x14x1.0 ExPad package: ✚ FC70 – Chorus 2M – assembled in Muar ✚ FC80 – Cut2.0 – Chorus 4M – assembled in Muar
MANUFACT. STEP	Final Test & Burn In & Finishing
INVOLVED PLANT	KESM TEST (M) SDN BHD – Malaysia
CHANGE REASON	Service – Dual source & Capacity Improvement. Expansion of current testing capacity (volumes increase) and flexible/secure production asset – dual sourcing strategy.
CHANGE DESCRIPTION	Activation of KESM as additional BE testing plant
TRACEABILITY	Dedicated Finished Good Code
VALIDATION	According to ZVEI (AEC-Q100/Q006) recommendations, item SEM-TF-01 *Move all or parts of electrical wafer test and/or final test to a different site*

	Device evaluation			Device evaluation			
	MATERIAL PERFORMANCE			MATERIAL		additional to AEC-	
Line evaluation (can be evaluated by data or audit/on site check)	**AEC-Q100 Revision H**	**Check of specification (for raw material only)**	Electrical Distribution ED E5	**AEC-Q101 Revision D**	Parametric Verification PV 4	Whisker test (IEC 60068-T2-82, JEDEC JESD201)	Parameter-Analysis: Comparison of current with changed device characterization, electrical
●	-	-	●	●	●	-	●

CURRENT PRODUCTS

Current products testing will be transferred to KESM. ST testing plants will remain active as alternative solution

REPORTS

Transfer validation is presently in progress. Testing transfer validation report for each product will be progressively available according to the qualification schedule.

IMPLEMENT.

Change activation is proposed upon ST full qualification, pending Customer approval. ***No customer sampling is planned***.

The Start of Production is foreseen for Q3’22 and will be progressive according to the qualification schedule.

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : SPC582BxxE1, SPC584BxxE1, SPC58xCxxE1, SPC584BxxE3, SPC58xCxxE3 (FC60,FC70,FC80): Activation of KESM as Additional Final Test and Burn-In Plant
PCN Reference : ADG/22/13479

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

SPC582B60E1CD00X	**SPC584B70E3CD00X**	**SPC584B64E1NH00X**
SPC582B60E1MH00Y	**SPC582B50E1CG00X**	**SPC584B70E1NHC0X**
SPC582B50E1AD00X	**SPC584B64E1DD00X**	**SPC584B60E3BDC0X**
SPC582B54E1CG00X	**SPC584B64E3CDC0X**	**SPC582B54E1BD00X**
SPC582B60E1MH00X	**SPC584B70E3NDC0Y**	**SPC584B70E1EDC0X**
SPC584B60E1EG00X	**SPC584B70E1EH00X**	**SPC584B70E3NMC0X**
SPC584B64E3ND00X	**SPC584B70E3EHC0X**	**SPC584B60E3MHC0X**

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